

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A high frequency laminated device comprising:  
a laminated body including
  - a first magnetic sheet having a relative permeability larger than 1,
  - a second magnetic sheet having a relative permeability larger than 1 [[on]] over a first surface of said first sheet, and
  - a third sheet under said first sheet;
  - a first inductor pattern for forming a first inductor and provided between said first and second sheets; and
  - first and second capacitor patterns forming a capacitor and situated between said first sheet and said third sheet.
2. (Currently Amended) The high frequency laminated device of claim 1, wherein said third sheet comprises at least one of a dielectric sheet and a magnetic sheet.
3. (Previously Presented) The high frequency laminated device of claim 2, wherein said first and third sheets are stacked and sintered after said first capacitor pattern is printed.
4. (Original) The high frequency laminated device of claim 1, further comprising a via-conductor formed in said first sheet, for electrically connecting said first inductor pattern and said first capacitor pattern.

5. (Original) The high frequency laminated device of claim 1, further comprising a circuit element mounted on a surface of said laminated body and connected to at least one of said first inductor and said capacitor.
6. (Original) The high frequency laminated device of claim 1, further comprising a second inductor pattern forming a second inductor provided between said first and second sheets.